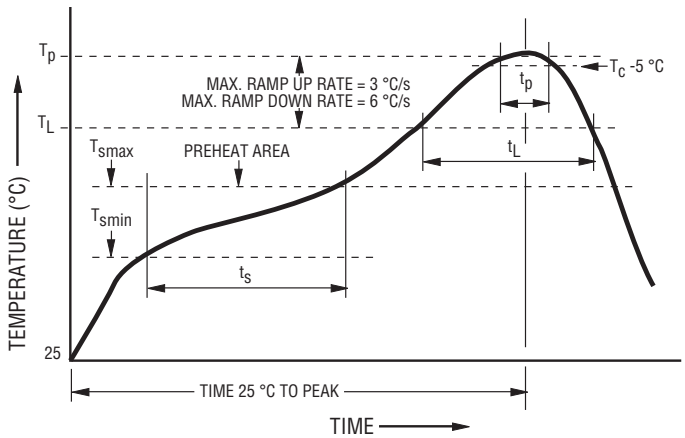
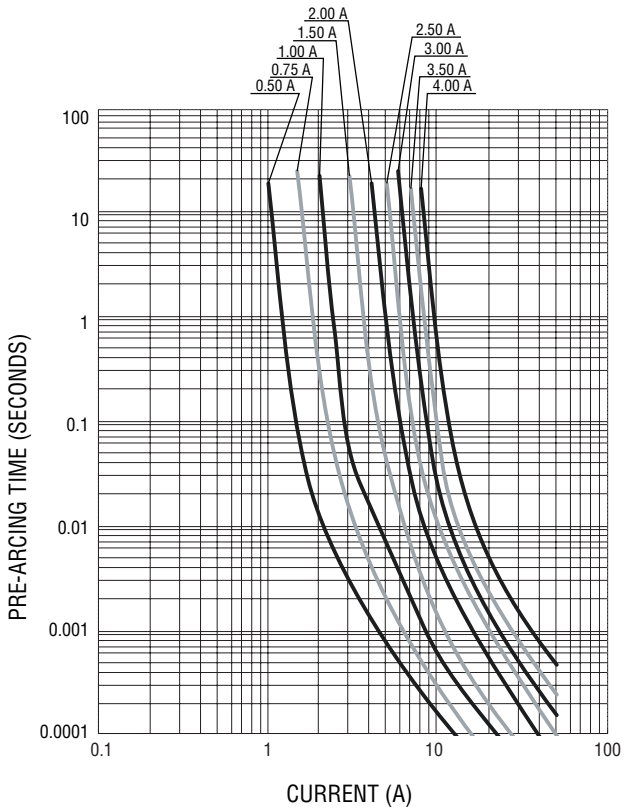
Solder Reflow Recommendations



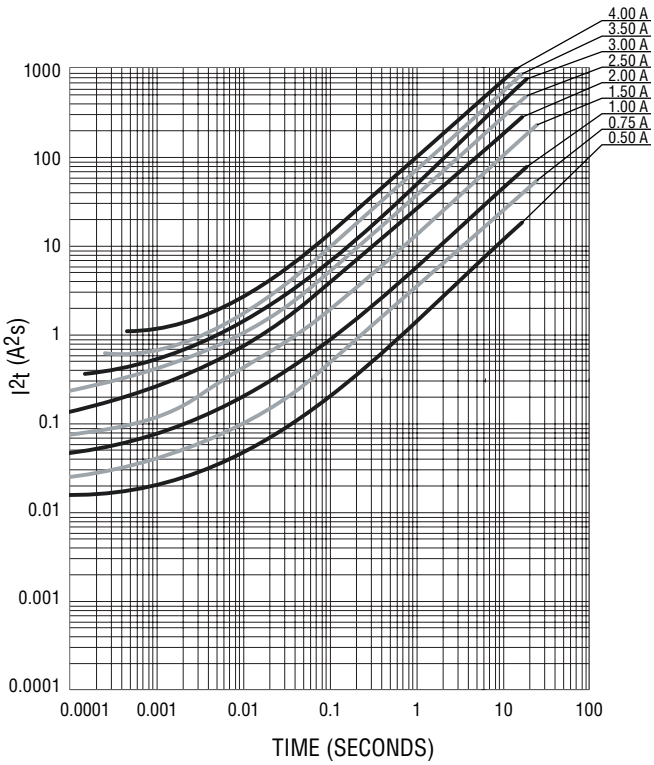
Profile Feature	Pb-Free Assembly
Preheat / Soak: Temperature Min. (T_{smin}) Temperature Max. (T_{smax}) Time (t_s) from (T_{smin} to T_{smax})	 150 °C 200 °C 60~120 seconds
Ramp Up Rate (T_L to T_p)	3 °C / second max.
Liquidous Temperature (T_L) Time (t_L) maintained above T_L	217 °C 60~150 seconds
Peak Package Body Temperature (T_p)	260 °C
Time (t_p)* within 5 °C of the specified classification temperature (T_c)	30 seconds*
Ramp Down Rate (T_p to T_L)	6 °C / second max.
Time 25 °C to Peak Temperature	8 minutes max.

* Tolerance for peak profile temperature (Tp) is defined as a supplier minimum and a user maximum.

Average Pre-Arcing Time vs. Current Curves



Average I^2t vs. t Curves



Specifications are subject to change without notice.
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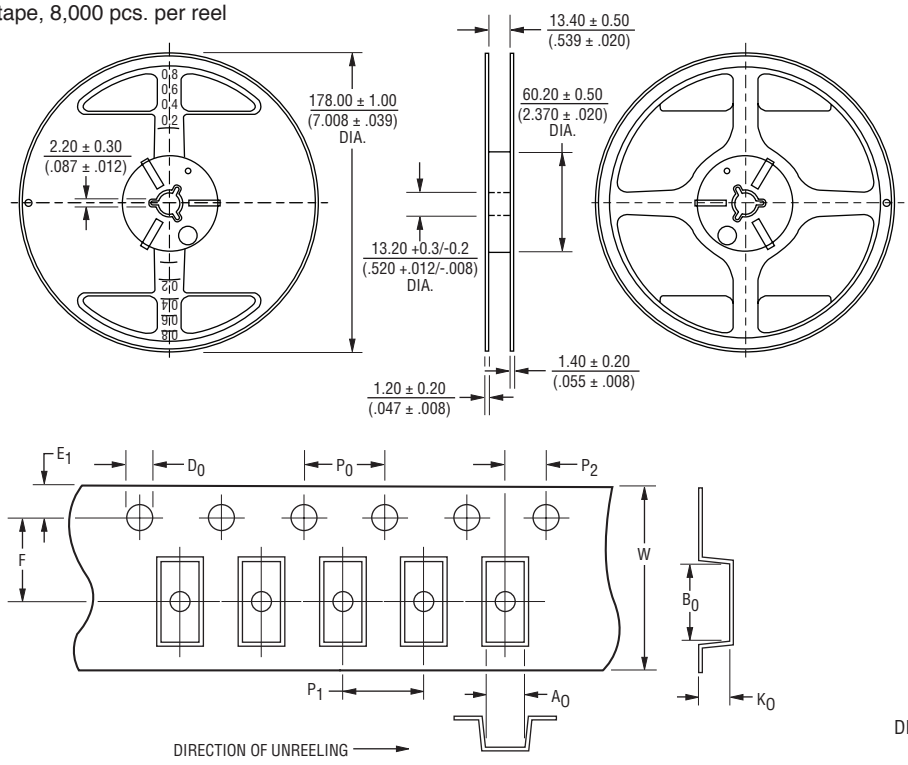
Tape Dimensions	SF-0603HIxxxF Series per EIA 481-2
W	8.10 ± 0.20 (.319 ± .008)
P_0	4.0 ± 0.10 (.157 ± .004)
P_1	4.0 ± 0.10 (.157 ± .004)
P_2	2.0 ± 0.05 (.079 ± .002)
A_0	1.00 ± 0.10 (.039 ± .004)
B_0	1.80 ± 0.10 (.071 ± .004)
F	3.50 ± 0.05 (.138 ± .002)
E_1	1.75 ± 0.10 (.069 ± .004)
D_0	1.55 + 0.05 (.061 + .002)

PACKAGING: Paper tape, 8,000 pcs. per reel



DIMENSIONS: MM / (INCHES)

REV. A 06/18

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